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<th>Top ID</th>
<th>Bottom ID</th>
<th>Date Generated</th>
<th>Revision</th>
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<tr>
<td>Layer Name</td>
<td>Notation</td>
<td>Slot Name</td>
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<tr>
<td>TOPKEY</td>
<td>T1000</td>
<td>T1001</td>
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<tr>
<td>BOTTOM</td>
<td>T1002</td>
<td>T1003</td>
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<tr>
<td>CENTER</td>
<td>T1004</td>
<td>T1005</td>
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</tbody>
</table>

**Notes:**
- All layers are oriented from top side.
- T1000 is the top layer.
- T1002 is the bottom layer.
- T1004 is the center layer.
- T1001 and T1003 are the slots for the top and bottom layers, respectively.
- T1005 is the slot for the center layer.

**Generate Date:** 4-14-2016

**Time:** 10:50:15 AM

**Company:** Texas Instruments
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